



Description

JMT P-channel Enhancement Mode Power MOSFET

Features

- -20V, -85A
- $R_{DS(ON)} < 2.7\text{m}\Omega$ @ $V_{GS} = -4.5\text{V}$
- $R_{DS(ON)} < 3.8\text{m}\Omega$ @ $V_{GS} = -2.5\text{V}$
- $R_{DS(ON)} < 5.7\text{m}\Omega$ @ $V_{GS} = -1.8\text{V}$
- Advanced Trench Technology
- Provide Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead free product is acquired

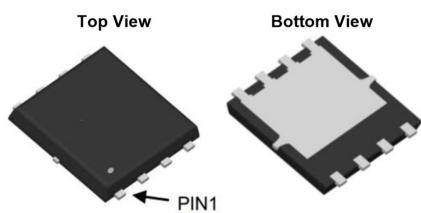
Application

- Load Switch
- PWM Application
- Power management

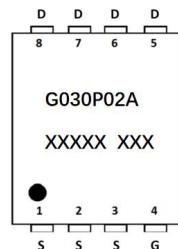


100% UIS TESTED!

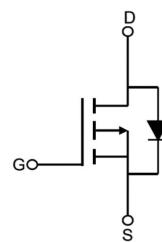
100% ΔV_{ds} TESTED!



PDFN5X6-8L



Marking and pin Assignment



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
G030P02A	JMTG030P02A	TAPING	PDFN5X6-8L	13inch	2500	25000

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		-20	V
V_{GSS}	Gate-Source Voltage		± 12	V
I_D	Continuous Drain Current	$T_C = 25^\circ\text{C}$	-85	A
		$T_C = 100^\circ\text{C}$	-55	A
I_{DM}	Pulsed Drain Current ^{note1}		-340	A
E_{AS}	Single Pulsed Avalanche Energy ^{note2}		154	mJ
P_D	Power Dissipation	$T_C = 25^\circ\text{C}$	33	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		3.8	$^\circ\text{C}/\text{W}$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$

**Electrical Characteristics** ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D = -250\mu\text{A}$	-20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -20\text{V}$, $V_{GS}=0\text{V}$,	-	-	-1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0\text{V}$, $V_{GS}= \pm 12\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D = -250\mu\text{A}$	-0.4	-	-1.0	V
$R_{DS(\text{on})}$	Static Drain-Source on-Resistance note2	$V_{GS} = -4.5\text{V}$, $I_D = -30\text{A}$	-	2.1	2.7	mΩ
		$V_{GS} = -2.5\text{V}$, $I_D = -20\text{A}$	-	2.7	3.8	
		$V_{GS} = -1.8\text{V}$, $I_D = -15\text{A}$	-	3.8	5.7	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS} = -10\text{V}$, $V_{GS}=0\text{V}$, $f=1.0\text{MHz}$	-	15	-	nF
C_{oss}	Output Capacitance		-	1600	-	pF
C_{rss}	Reverse Transfer Capacitance		-	1068	-	pF
Q_g	Total Gate Charge	$V_{DS} = -10\text{V}$, $I_D = -20\text{A}$, $V_{GS} = -4.5\text{V}$	-	100	-	nC
Q_{gs}	Gate-Source Charge		-	21	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	32	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = -10\text{V}$, $R_L=0.5\Omega$, $V_{GS} = -4.5\text{V}$, $R_{\text{GEN}}=3\Omega$	-	20	-	ns
t_r	Turn-on Rise Time		-	50	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	100	-	ns
t_f	Turn-off Fall Time		-	40	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain to Source Diode Forward Current	-	-	-85	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	-340	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$, $I_s = -30\text{A}$	-	-0.8	-1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2.EAS condition: $T_J=25^\circ\text{C}$, $V_{DD}=-10\text{V}$, $V_G=-10\text{V}$, $R_G=25\Omega$, $L=0.5\text{mH}$, $I_{AS}=-24.8\text{A}$

3.Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%

Typical Performance Characteristics

Figure 1: Output Characteristics

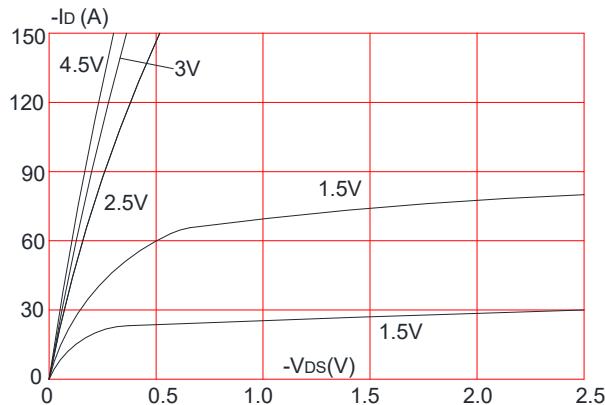


Figure 3: On-resistance vs. Drain Current

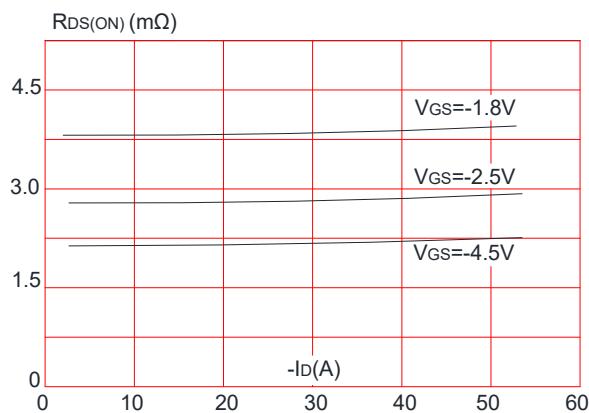


Figure 5: Gate Charge Characteristics

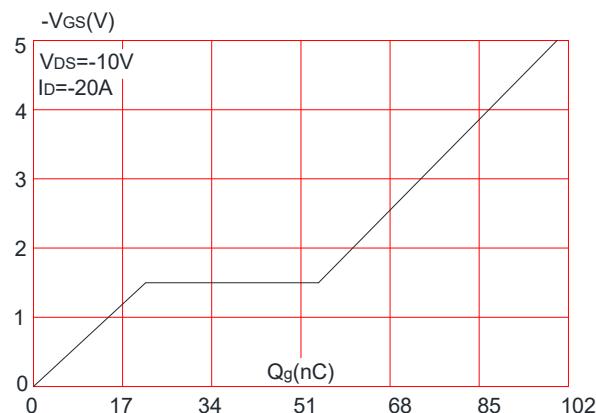


Figure 2: Typical Transfer Characteristics

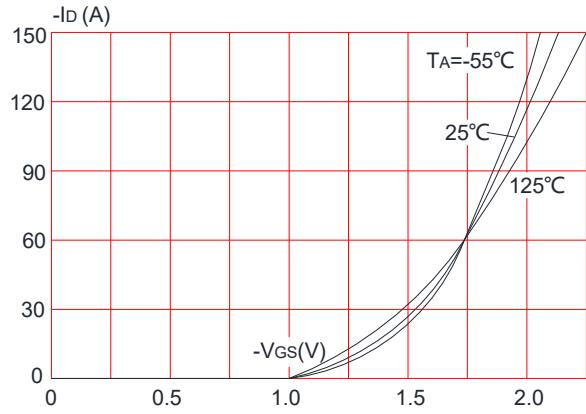


Figure 4: Body Diode Characteristics

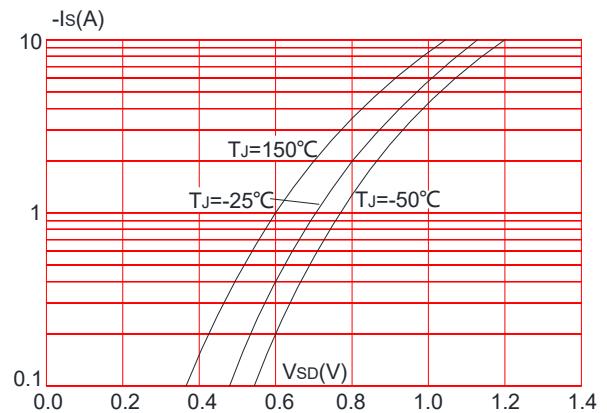


Figure 6: Capacitance Characteristics

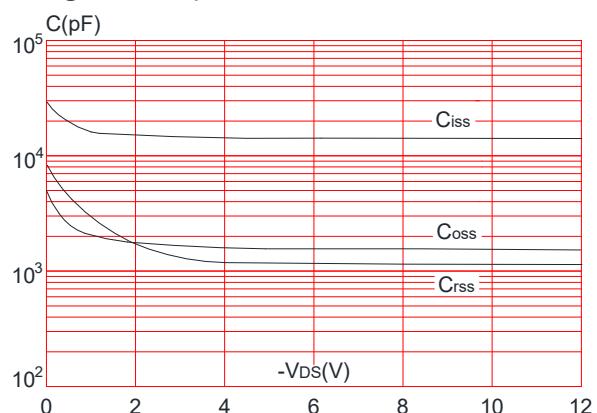


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

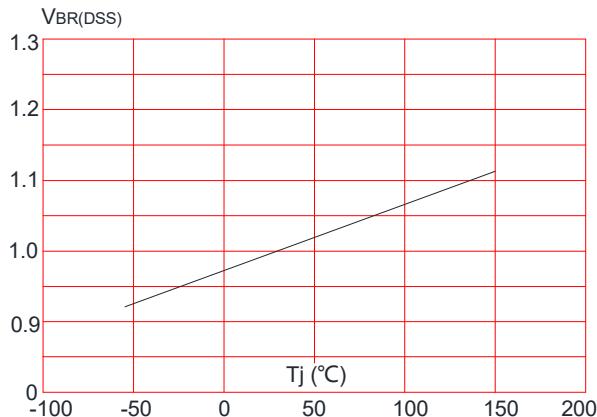


Figure 9: Maximum Safe Operating Area

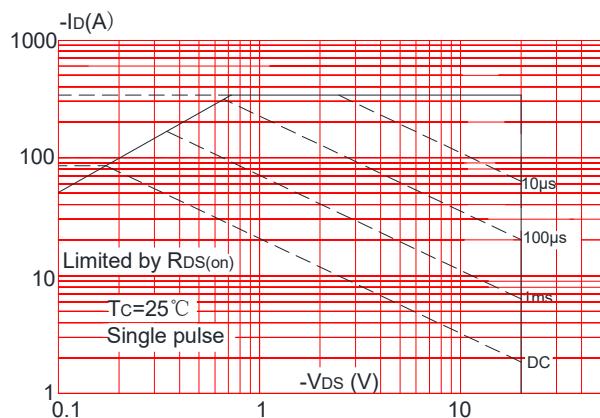


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

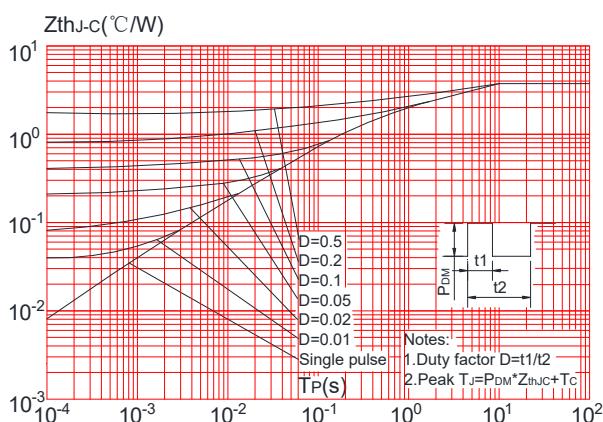


Figure 8: Normalized on Resistance vs. Junction Temperature

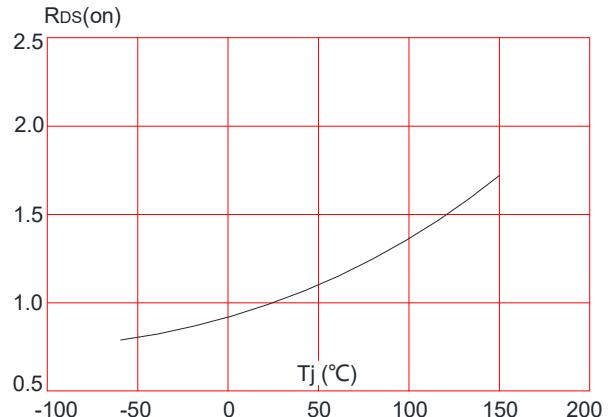
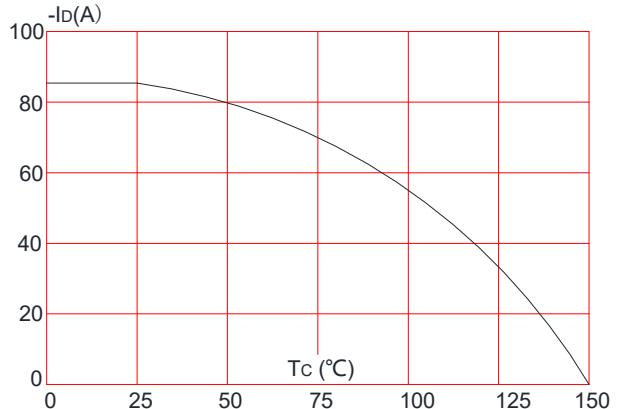
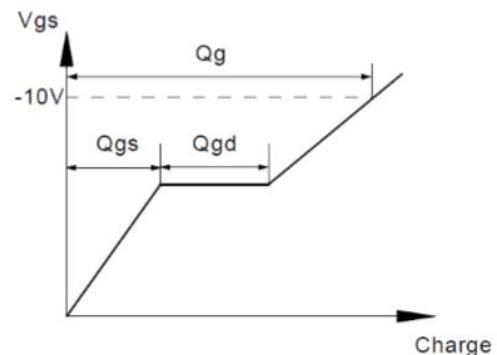
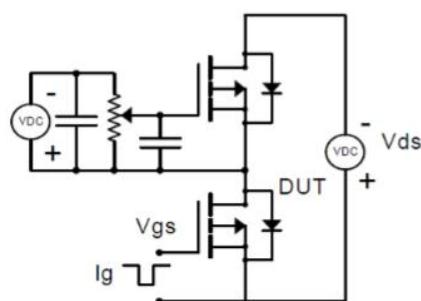


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

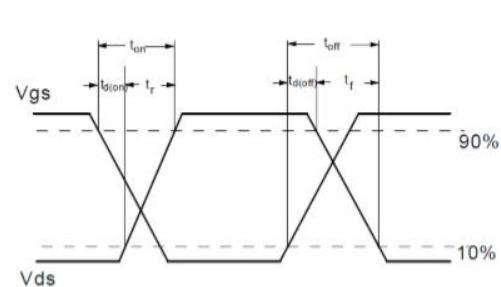
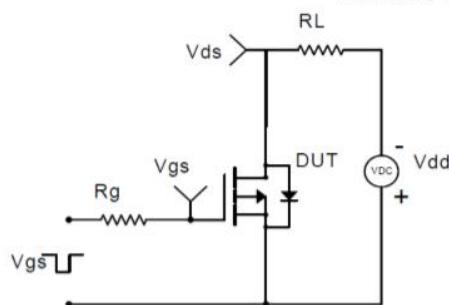


Test Circuit

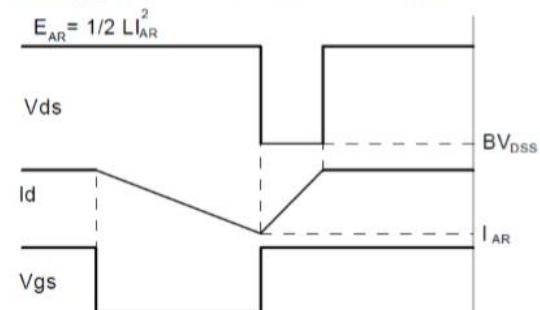
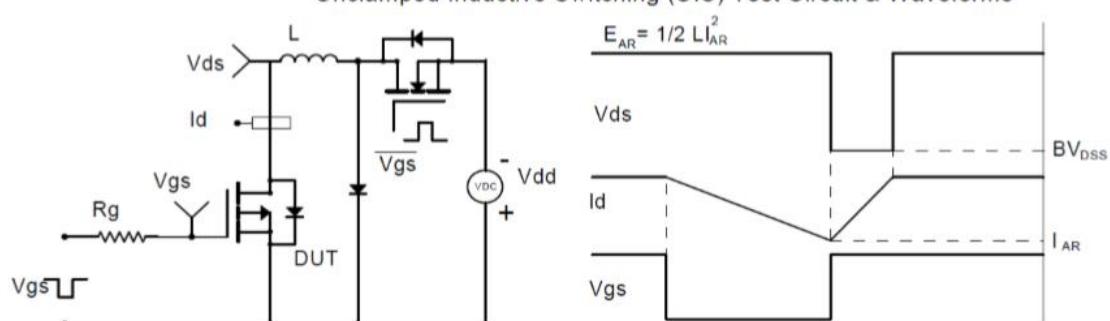
Gate Charge Test Circuit & Waveform



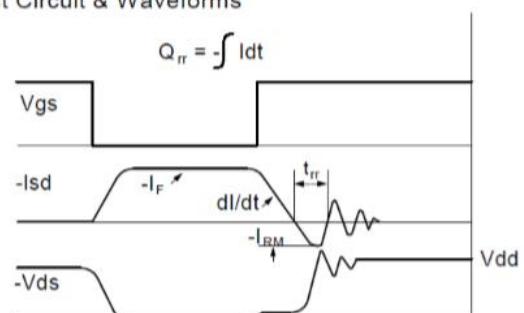
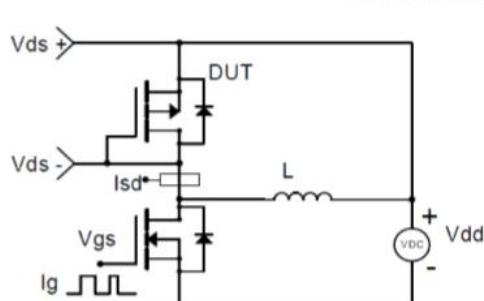
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

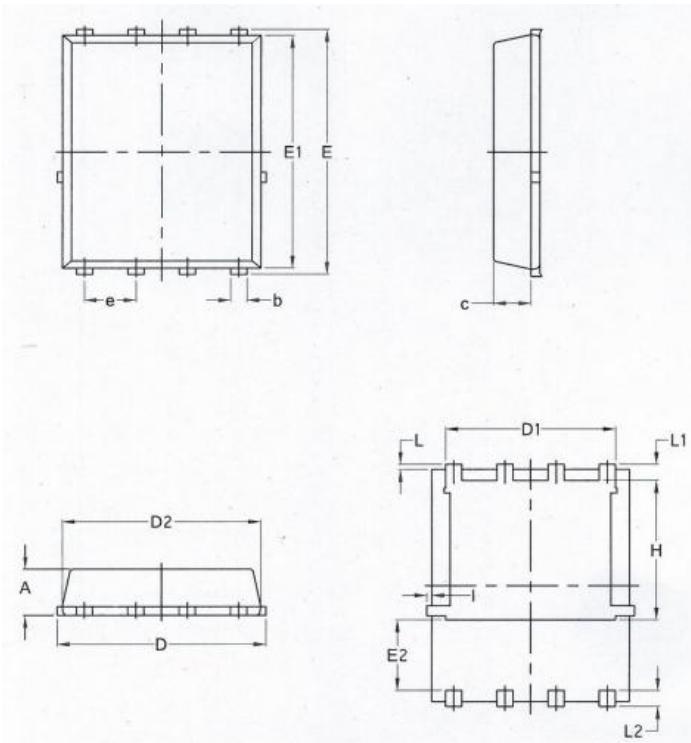


Diode Recovery Test Circuit & Waveforms





Package Mechanical Data- PDFN5X6-8L



SYMBOL	COMMON			
	MM		INCH	
	MIN.	MAX.	MIN.	MAX.
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.970	0.0324	0.0382
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	—	0.0630	—
e	1.27	BSC	0.05	BSC
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	—	0.18	—	0.0070

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